

**Description**: 1.575 GHz GNSS Ceramic Chip Antenna

Series: Ceramic Chip Antenna

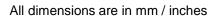
PART NUMBER: W3011A

### **Features:**

- Frequency 1559-1606.6MHz
- Gain 1.3 / 2.0 / 2.2dBi
- Size 3.2 x 1.6 x 1.1 mm
- PCB Keep out 4 x 6.25 mm
- Polarization Linear
- Radiation pattern Omni

# Applications:

- L1 GNSS Receivers
- Beidou, GPS, Galileo Glonass
- IoT, M2M
- Asset tracking
- Portable satellite receivers



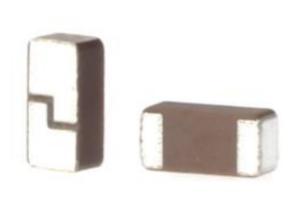
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### **ELECTRICAL SPECIFICATIONS**

Chip antenna
1559-1563MHz
1574.4-1576.4MHz
1598.6-1606.6MHz
50 Ω
-7 / -10 / -10 dB
Omni
1.3 / 2.0 / 2.2dBi
65 / 75 / 78 %
Vertical
2W

### **MECHANICAL SPECIFICATIONS**

Compact size	3.2 x 1.6 x 1.1mm
Weight	0.033g
Fixing system	SMT
MSL(MOISTURE SENSITIVITY LEVEL)	1

### **ENVIRONMENTAL SPECIFICATIONS**

Operating Temperature Storage Temperature RoHS Compliant -40 ~ +85° C -40 ~ +85° C Yes

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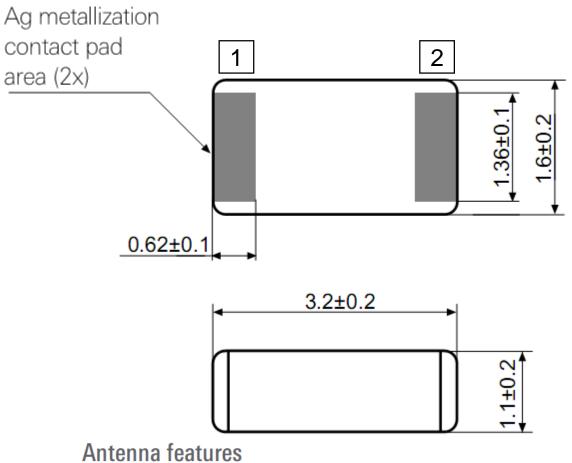


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## **MECHANICAL DRAWING**



No.	Terminal name	Terminal Dimensions
1	Feed / GND	0.62 x 1.36 mm
2	Feed / GND	0.62 x 1.36 mm

Antenna is symmetrical.

Either of terminals 1 or 2 can be feed / GND

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### W3011 GPS Antenna PWB Layout

Ground cleared under antenna, clearance area 4.00 x 6.25 mm Matching and tuning component value and placement depend on application and surrounding mechanics / materials.

Feed line should be designed to match 50  $\Omega$  characteristic impedance, depending on PWB material and thickness. Recommended test board layout for electrical characteristic measurement, test board outline size 80 x 37 mm.



2



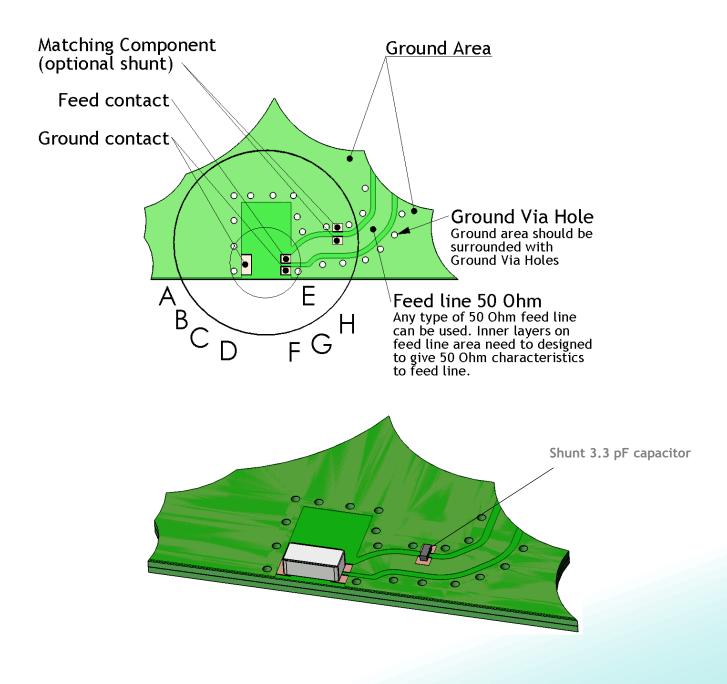
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### PWB layout for W3011A GPS Antenna

Note: All dimensions are in metric system.



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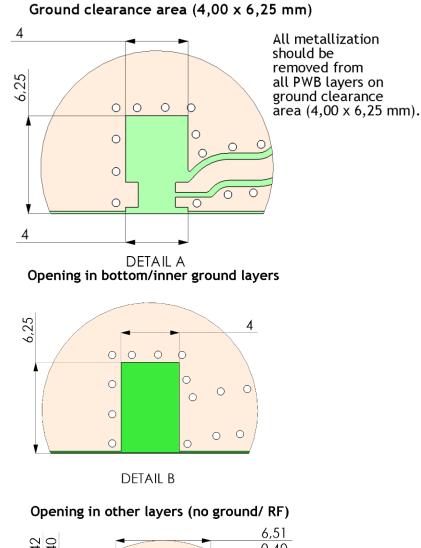


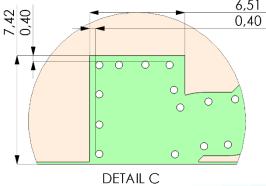
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### Ground clearance area for W3011A GPS Antenna





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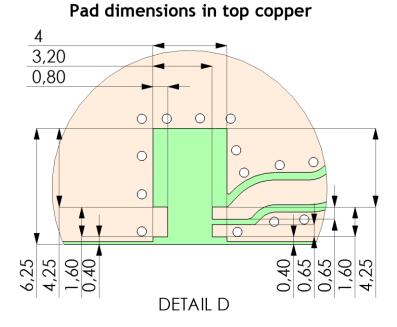


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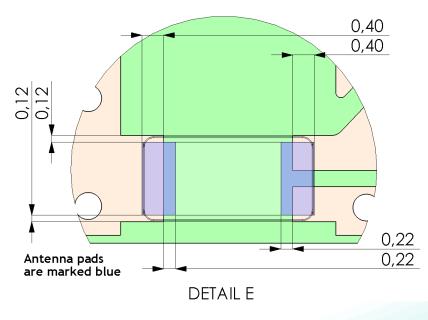
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### PWB pad dimensions and antenna position for W3011A GPS Antenna



### Antenna position on PWB layout



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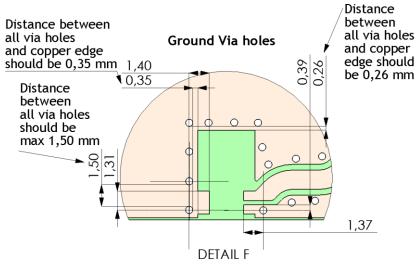


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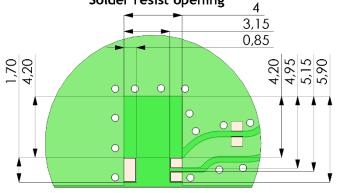
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### Typical Ground via hole placement in PWB layout for W3011A GPS Antenna

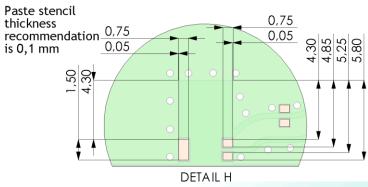


### Solder resist opening and paste stencil recommendations for W3011A GPS Antenna Solder resist opening





Paste stencil recommendation



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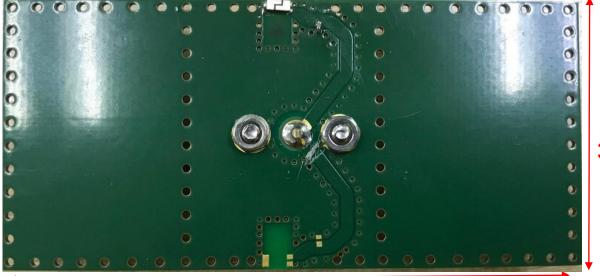
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### **TEST SETUP**

All RF parameters tested on 80x37mm sized test board. Antenna position on side center of PCB long edge.



37mm

80mm

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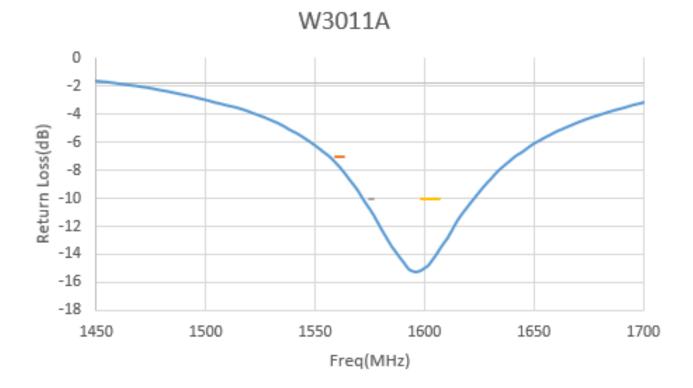
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**CHARTS** 

Return Loss vs Frequency



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ROHS 10



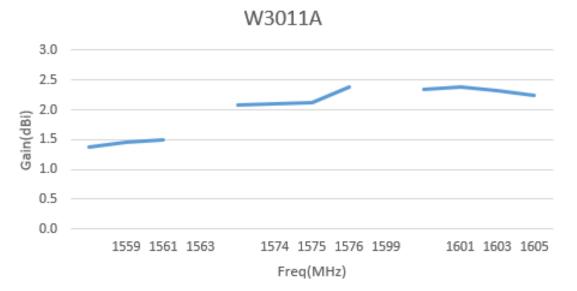
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CHARTS

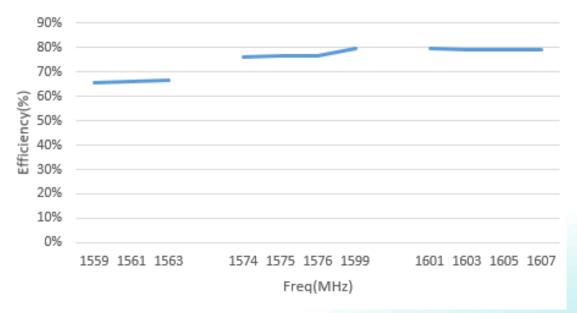
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# Gain vs Frequency



# Radiation Efficiency vs Frequency

W3011A



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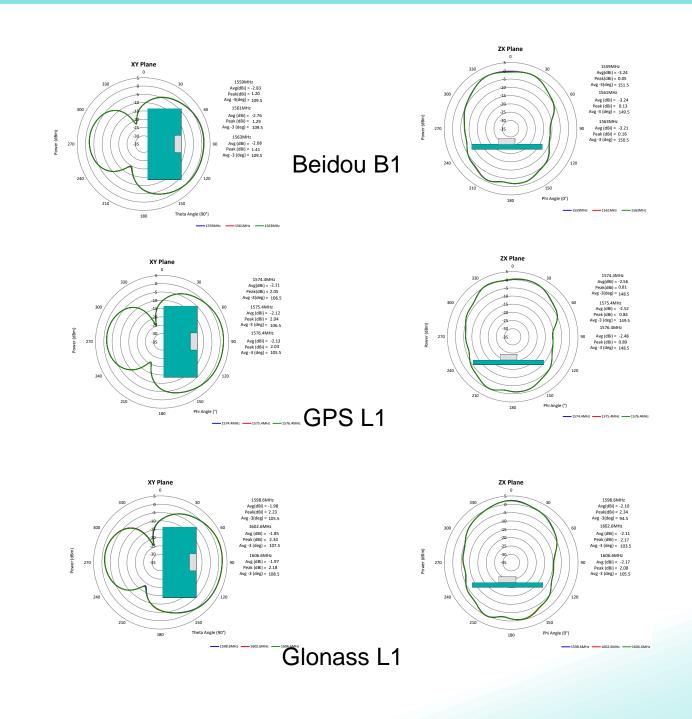


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### **CHARTS**



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TECHNICAL DATA SHEET

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### .

### **Recommendation for reflow soldering process**

Printing stencil thickness 0,15 - 0,25 mm is recommended for the solder paste. The maximum soldering temperature should not exceed 260°C. The temperature profile recommendations for reflow soldering process is presented in the Figures 1 and 2. The reflow profile presented in figure 1 describes minimum reflow temperatures. The reflow profile presented in figure 2 describes maximum reflow temperatures. located at the center of the coverage area.

	Method of heat transfer	Controlled hot air convection	
1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 30 sec	
5	Peak temperature in reflow	230 °C for 10 seconds	
6	Temperature gradient in cooling	Max -5 °C/s	

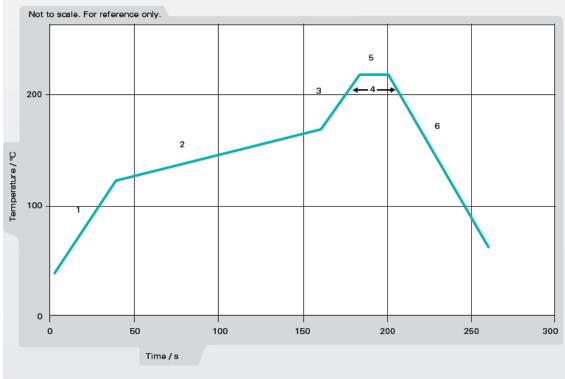


Figure 1. Minimum temperature profile recommendation for reflow soldering process

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1	Average temperature gradient in preheating	2.5 °C/s	
2	Soak time	2-3 minutes	
3	Max temperature gradient in reflow	3 °C/s	
4	Time above 217 °C	Max 60 sec	
5	Time above 230 °C	Max 50 sec	
6	Time above 250 °C	Max 10 sec	
7	Peak temperature in reflow	260 °C for 5 seconds	
8	Temperature gradient in cooling	Max -5 °C/s	

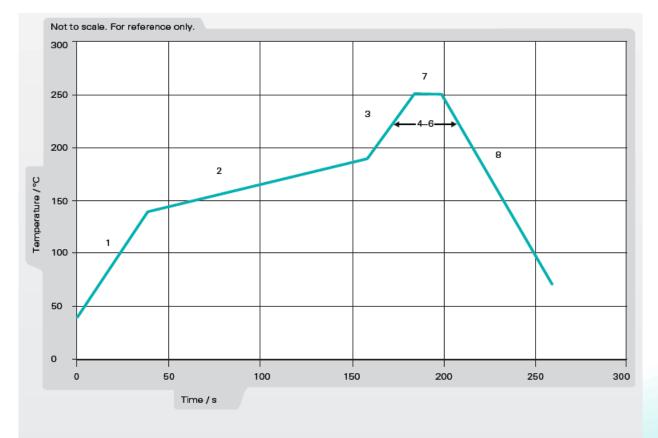


Figure 2. Maximum temperature profile recommendation for reflow soldering process

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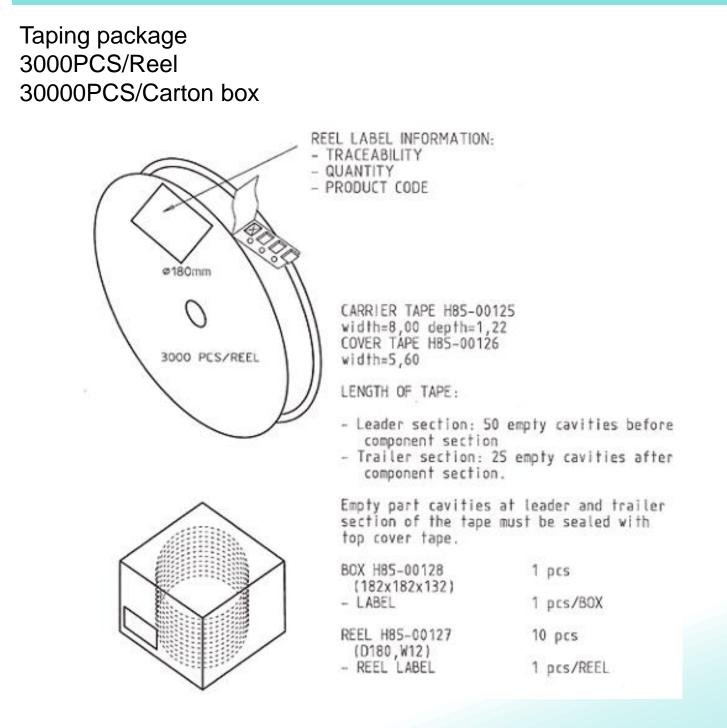


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### PACKAGING



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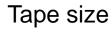


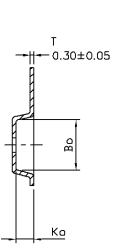
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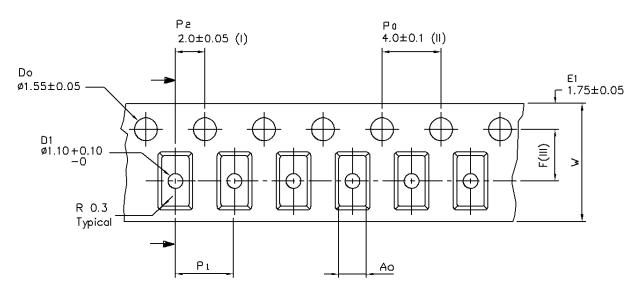
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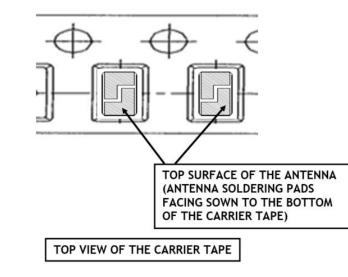
PACKAGING







Ao	1.85	+/- 0.1
Bo	3.43	+/- 0.1
Ко	1.22	+/- 0.1
F	3.50	+/- 0.05
Ρ1	4.00	+/- 0.1
W	8.00	+/- 0.1



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